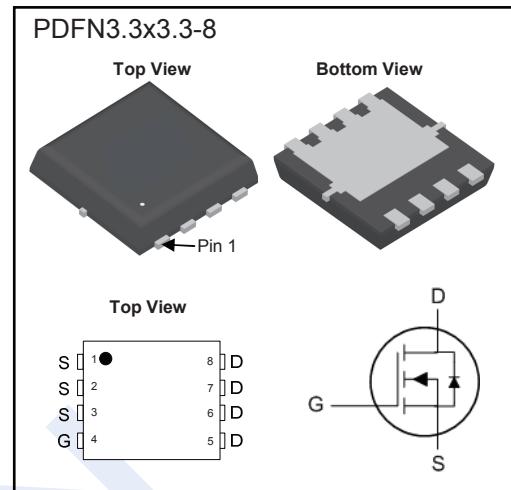


## N-Channel MOSFET

## KI60N03DFN

## ■ Features

- $V_{DS}$  (V) = 30 V
- $I_{D\text{MAX}}$  = 60 A
- $R_{DS(\text{ON})}$  (at  $V_{GS}$  = 10 V) < 7 mΩ

■ Absolute Maximum Ratings ( $T_A$  = 25°C unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current, $V_{GS}$ @ 10V (Note 1)	$I_D$	60	A
		38	
		20	
		12.7	
		16	
		10.2	
Pulsed Drain Current (Note 2)	$I_{DM}$	180	
Avalanche Current	$I_{AS}$	48	
Single Pulse Avalanche Energy (Note 3)	$E_{AS}$	252	mJ
Power Dissipation (Note 4)	$P_D$	37	W
		4.2	
		1.67	
Thermal Resistance.Junction- to-Ambient (Note 1)	$R_{thJA}$	75	°C/W
		30	
Thermal Resistance.Junction- to-Case (Note 1)	$R_{thJC}$	3.36	
Junction Temperature	$T_J$	150	
Storage Temperature Range	$T_{stg}$	-55 to 150	°C

## N-Channel MOSFET

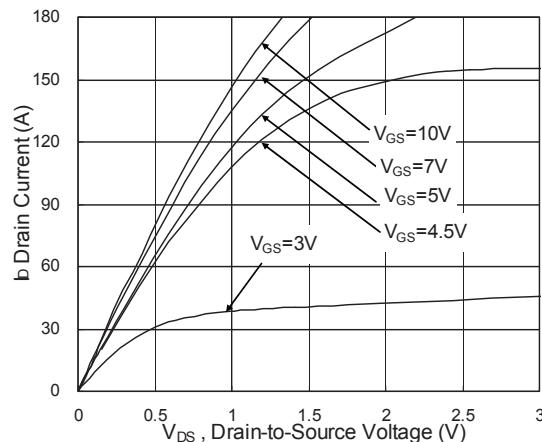
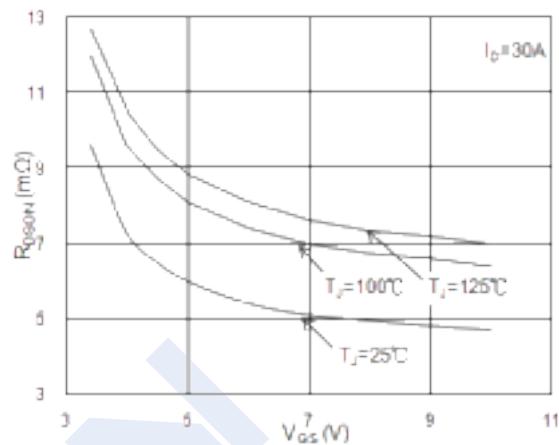
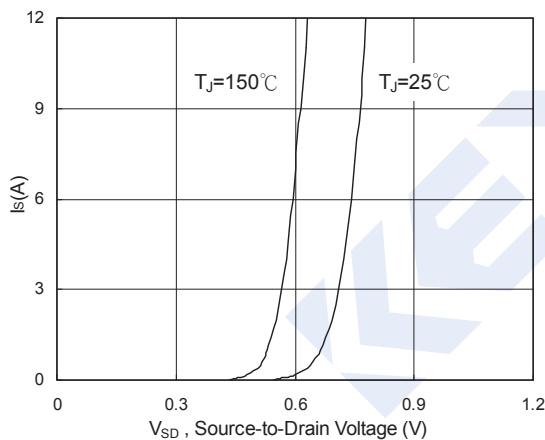
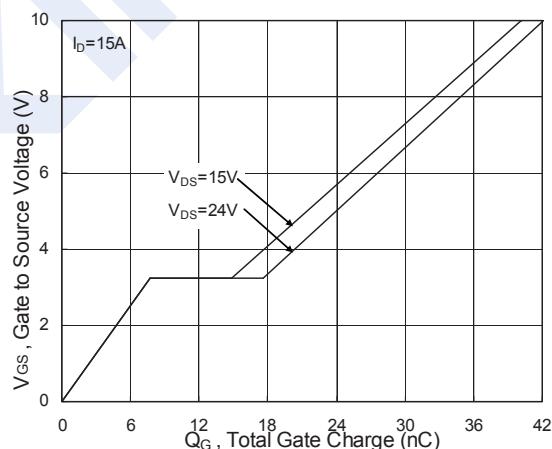
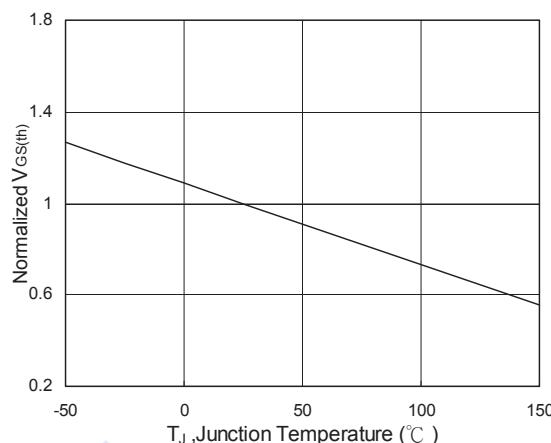
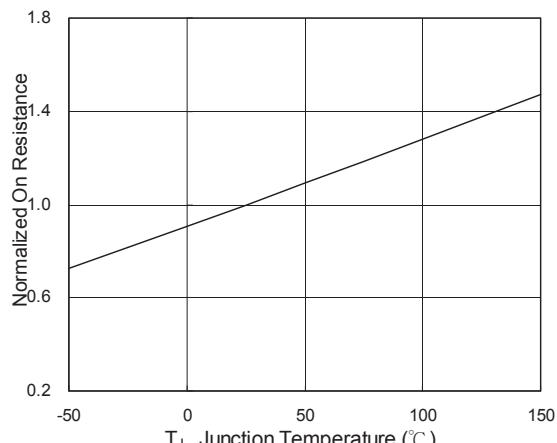
## KI60N03DFN

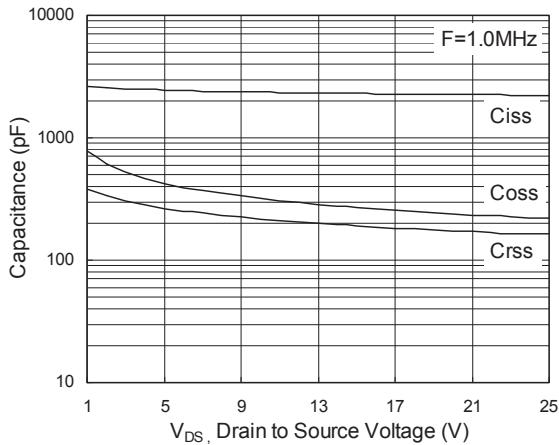
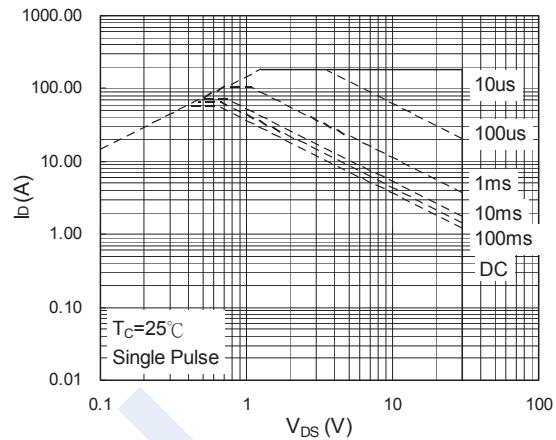
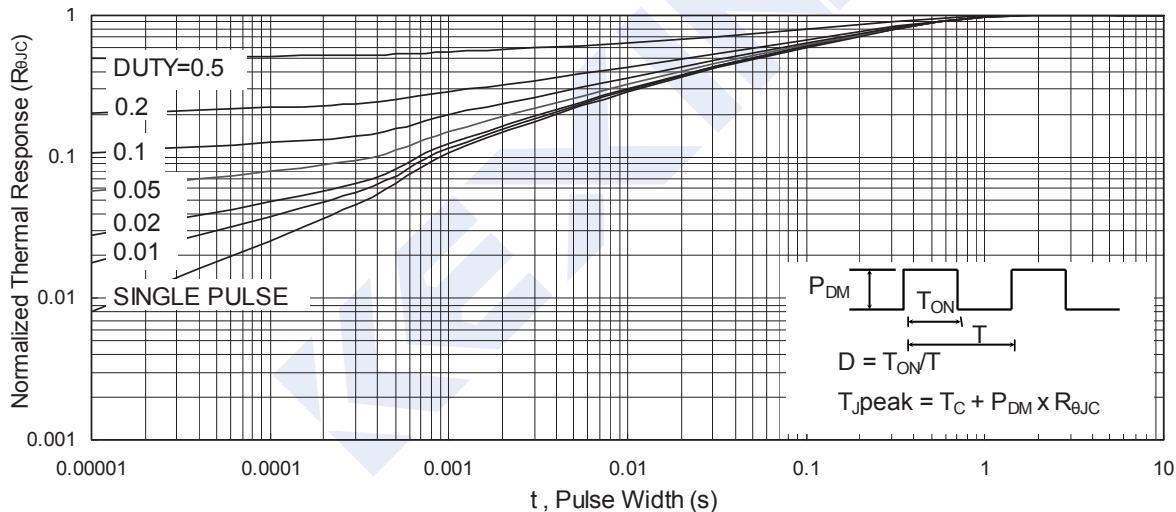
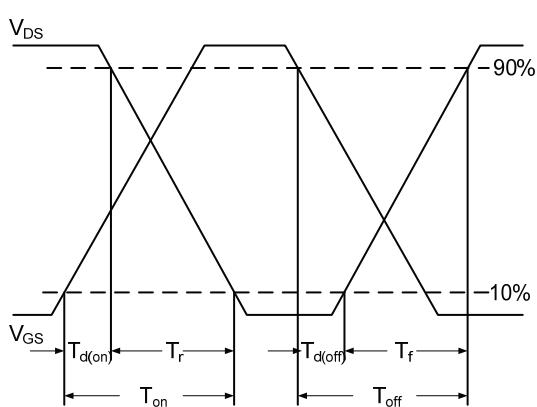
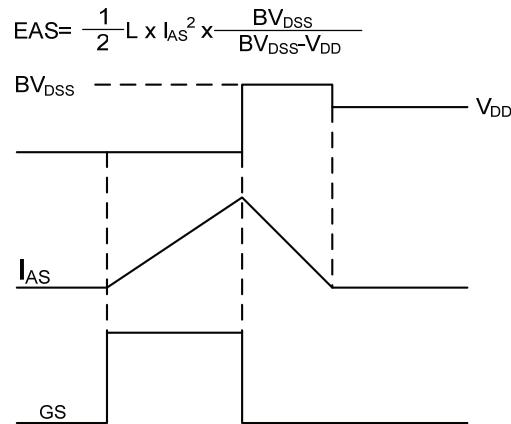
■ Electrical Characteristics ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$\text{ID} = 250 \mu\text{A}, \text{V}_{\text{GS}} = 0 \text{V}$	30			V
Zero Gate Voltage Drain Current	$\text{Id}_{\text{SS}}$	$\text{V}_{\text{DS}} = 24 \text{V}, \text{V}_{\text{GS}} = 0 \text{V}$		1		$\mu\text{A}$
		$\text{V}_{\text{DS}} = 24 \text{V}, \text{V}_{\text{GS}} = 0 \text{V}, T_J = 55^\circ\text{C}$		5		
Gate to Source Leakage Current	$\text{I}_{\text{GSS}}$	$\text{V}_{\text{DS}} = 0 \text{V}, \text{V}_{\text{GS}} = \pm 20 \text{V}$			$\pm 100$	nA
Gate to Source Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{DS}} = \text{V}_{\text{GS}}, \text{ID} = 250 \mu\text{A}$	1.2		2.5	V
Static Drain-Source On-Resistance (Note 2)	$\text{R}_{\text{DS(on)}}$	$\text{V}_{\text{GS}} = 10 \text{V}, \text{ID} = 30 \text{A}$		7		$\text{m}\Omega$
		$\text{V}_{\text{GS}} = 4.5 \text{V}, \text{ID} = 15 \text{A}$		10		
Forward Transconductance	$\text{g}_{\text{FS}}$	$\text{V}_{\text{DS}} = 5 \text{V}, \text{ID} = 30 \text{A}$		43		S
Input Capacitance	$\text{C}_{\text{iss}}$	$\text{V}_{\text{GS}} = 0 \text{V}, \text{V}_{\text{DS}} = 15 \text{V}, f = 1 \text{MHz}$		2295	3213	$\text{pF}$
Output Capacitance	$\text{C}_{\text{oss}}$			267	374	
Reverse Transfer Capacitance	$\text{C}_{\text{rss}}$			210	294	
Gate Resistance	$\text{R}_g$	$\text{V}_{\text{GS}} = 0 \text{V}, \text{V}_{\text{DS}} = 0 \text{V}, f = 1 \text{MHz}$		1.6	2.8	$\Omega$
Single Pulse Avalanche Energy (Note 5)	$\text{E}_{\text{AS}}$	$\text{V}_{\text{DD}}=25\text{V}, L=0.1\text{mH}, I_{\text{AS}}=24\text{A}$	63			$\text{mJ}$
Total Gate Charge	$\text{Q}_{\text{g}}(4.5\text{V})$	$\text{V}_{\text{GS}} = 4.5\text{V}, \text{V}_{\text{DS}} = 15 \text{V}, \text{ID} = 15 \text{A}$		20	28	$\text{nC}$
Gate Source Charge	$\text{Q}_{\text{gs}}$			7.6	10.6	
Gate Drain Charge	$\text{Q}_{\text{gd}}$			7.2	10.1	
Turn-On Delay Time	$\text{t}_{\text{d(on)}}$	$\text{V}_{\text{GS}} = 10\text{V}, \text{V}_{\text{DD}} = 15 \text{V}, \text{R}_g = 3.3 \Omega, \text{ID} = 15\text{A}$		7.8	15.6	$\text{ns}$
Turn-On Rise Time	$\text{t}_{\text{r}}$			15	27	
Turn-Off Delay Time	$\text{t}_{\text{d(off)}}$			37.3	75	
Turn-Off Fall Time	$\text{t}_{\text{f}}$			10.6	21.2	
Body Diode Reverse Recovery Time	$\text{t}_{\text{rr}}$	$I_{\text{F}} = 30 \text{ A}, \text{di/dt} = 100 \text{ A}/\mu\text{s}$		14		$\text{nC}$
Body Diode Reverse Recovery Charge	$\text{Q}_{\text{rr}}$			5		
Maximum Body-Diode Continuous Current (Note 1,6)	$\text{I}_{\text{S}}$	$\text{V}_{\text{G}}=\text{V}_{\text{D}}=0\text{V}, \text{Force Current}$			60	$\text{A}$
Pulsed Source Current (Note 2,6)	$\text{I}_{\text{SM}}$				180	
Diode Forward Voltage (Note 2)	$\text{V}_{\text{SD}}$	$\text{V}_{\text{GS}} = 0 \text{V}, \text{IS} = 1 \text{A}$			1	V

Notes:

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $\text{V}_{\text{DD}}=25\text{V}, \text{V}_{\text{GS}}=10\text{V}, \text{L}=0.1\text{mH}, \text{I}_{\text{AS}}=48\text{A}$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The Min. value is 100% EAS tested guarantee.
- 6.The data is theoretically the same as  $\text{ID}$  and  $\text{ID}_{\text{M}}$  , in real applications , should be limited by total power dissipation.

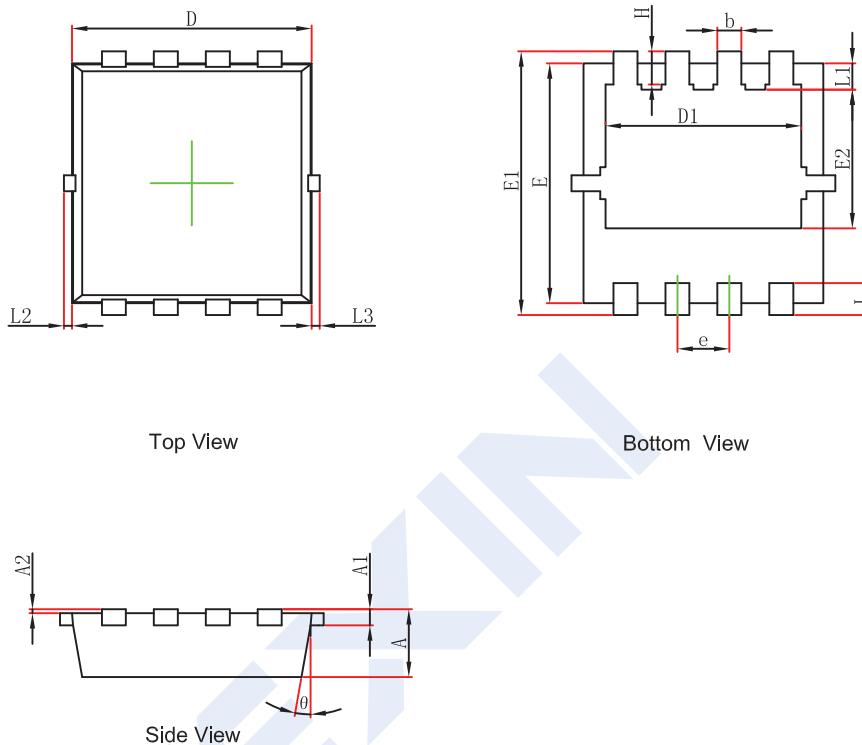
**N-Channel MOSFET****KI60N03DFN****■ Typical Characteristics****Fig.1 Typical Output Characteristics****Fig.2 On-Resistance vs. G-S Voltage****Fig.3 Forward Characteristics Of Reverse****Fig.4 Gate-Charge Characteristics****Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$** **Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**

**N-Channel MOSFET****KI60N03DFN****Fig.7 Capacitance****Fig.8 Safe Operating Area****Fig.9 Normalized Maximum Transient Thermal Impedance****Fig.10 Switching Time Waveform****Fig.11 Unclamped Inductive Switching Waveform**

## N-Channel MOSFET

## KI60N03DFN

## ■ PDFN3.3x3.3-8 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.650	0.850	0.026	0.033
A1	0.152	REF.	0.006	REF.
A2	0~0.05		0~0.002	
D	2.900	3.100	0.114	0.122
D1	2.300	2.600	0.091	0.102
E	2.900	3.100	0.114	0.122
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0~0.100		0~0.004	
L3	0~0.100		0~0.004	
H	0.315	0.515	0.012	0.020
θ	9°	13°	9°	13°